

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr> <td>Harry Hak-Lay CHUANG</td> <td>01/28/2011</td> </tr> <tr> <td>Bao-Ru YOUNG</td> <td>01/28/2011</td> </tr> <tr> <td>Ming ZHU</td> <td>01/28/2011</td> </tr> <tr> <td>Hui-Wen LIN</td> <td>01/28/2011</td> </tr> <tr> <td>Lee-Wee TEO</td> <td>01/28/2011</td> </tr> </tbody> </table>		Name	Execution Date	Harry Hak-Lay CHUANG	01/28/2011	Bao-Ru YOUNG	01/28/2011	Ming ZHU	01/28/2011	Hui-Wen LIN	01/28/2011	Lee-Wee TEO	01/28/2011
Name	Execution Date												
Harry Hak-Lay CHUANG	01/28/2011												
Bao-Ru YOUNG	01/28/2011												
Ming ZHU	01/28/2011												
Hui-Wen LIN	01/28/2011												
Lee-Wee TEO	01/28/2011												
RECEIVING PARTY DATA													
<table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 20%;">Name:</td> <td>TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.</td> </tr> <tr> <td>Street Address:</td> <td>No. 8, Li-Hsin Rd. VI, Hsinchu Science Park</td> </tr> <tr> <td>City:</td> <td>Hsinchu</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300</td> </tr> </table>		Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.	Street Address:	No. 8, Li-Hsin Rd. VI, Hsinchu Science Park	City:	Hsinchu	State/Country:	TAIWAN	Postal Code:	300		
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.												
Street Address:	No. 8, Li-Hsin Rd. VI, Hsinchu Science Park												
City:	Hsinchu												
State/Country:	TAIWAN												
Postal Code:	300												
PROPERTY NUMBERS Total: 1													
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 30%;">Property Type</th> <th style="width: 70%;">Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13025956</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13025956								
Property Type	Number												
Application Number:	13025956												
CORRESPONDENCE DATA													
<p>Fax Number: (703)518-5499</p> <p><i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 7036841111</p> <p>Email: sramunto@ipfirm.com</p> <p>Correspondent Name: Lowe Hauptman Ham & Berner, LLP (TSMC)</p> <p>Address Line 1: 1700 Diagonal Road, Suite 300</p> <p>Address Line 4: Alexandria, VIRGINIA 22314</p>													
ATTORNEY DOCKET NUMBER:	T5057-Y411												
NAME OF SUBMITTER:	Randy A. Noranbrock												

OP \$40.00 13025956

501436426

PATENT
REEL: 025798 FRAME: 0722

Total Attachments: 1
source=efiledassgn#page1.tif

Docket No. T5057-Y411

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- | | |
|-------------------------|----------------|
| 1) Harry Hak-Lay CHUANG | 4) Hui-Wen LIN |
| 2) Bao-Ru YOUNG | 5) Lee-Wee TEO |
| 3) Ming ZHU | |

who has made a certain new and useful invention, hereby sells, assigns and transfers unto

TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD. having a place of business at No. **8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan R.O.C.**

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

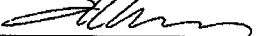
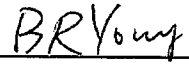
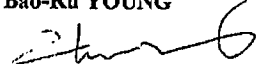
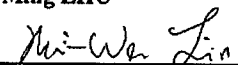

METAL GATE STRUCTURE OF A CMOS SEMICONDUCTOR DEVICE

- (a) for which an application for United States Letters Patent was filed on 2-11-2011, and identified by United States Patent Application No. 13/025,956; or
- (b) for which an application for United States Letters Patent was executed on _____,

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

- 1) 
Name: Harry Hak-Lay CHUANG
- 2) 
Name: Bao-Ru YOUNG
- 3) 
Name: Ming ZHU
- 4) 
Name: Hui-Wen LIN
- 5) 
Name: Lee-Wee TEO

1/28/2011
Date:

1/28/2011
Date:

1/28/2011
Date:

1/28/11
Date:

1/28/11
Date: